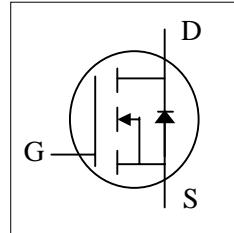
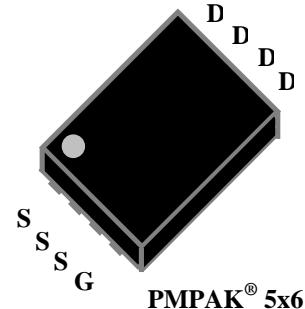




- ▼ Simple Drive Requirement
- ▼ SO-8 Compatible with Heatsink
- ▼ Low On-resistance
- ▼ RoHS Compliant & Halogen-Free



BV_{DSS}	60V
$R_{DS(ON)}$	5mΩ
I_D	84A



Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The PMPAK® 5x6 package is special for DC-DC converters application and the foot print is compatible with SO-8 with backside heat sink and lower profile.

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	+20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current (Chip)	84	A
$I_D @ T_A = 25^\circ C$	Continuous Drain Current ³	23.8	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current ³	19	A
I_{DM}	Pulsed Drain Current ¹	240	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	62.5	W
$P_D @ T_A = 25^\circ C$	Total Power Dissipation	5	W
E_{AS}	Single Pulse Avalanche Energy ⁴	28.8	mJ
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Units
R_{thj-c}	Maximum Thermal Resistance, Junction-case	2.0	°C/W
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient ³	25	°C/W



Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	60	-	-	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=30\text{A}$	-	-	5	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}$, $\text{I}_D=250\mu\text{A}$	2	-	5	V
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=10\text{V}$, $\text{I}_D=30\text{A}$	-	55	-	S
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=48\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$	-	-	25	μA
I_{GSS}	Gate-Source Leakage	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Q_{g}	Total Gate Charge ²	$\text{I}_D=30\text{A}$	-	53	84	nC
Q_{gs}	Gate-Source Charge	$\text{V}_{\text{DS}}=30\text{V}$	-	15	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$\text{V}_{\text{GS}}=10\text{V}$	-	24	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time ²	$\text{V}_{\text{DS}}=30\text{V}$	-	16	-	ns
t_r	Rise Time	$\text{I}_D=1\text{A}$	-	15	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time	$\text{R}_G=3.3\Omega$, $\text{V}_{\text{GS}}=10\text{V}$	-	35	-	ns
t_f	Fall Time	$\text{R}_D=30\Omega$	-	37	-	ns
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}$	-	2320	3700	pF
C_{oss}	Output Capacitance	$\text{V}_{\text{DS}}=25\text{V}$	-	450	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	280	-	pF
R_{g}	Gate Resistance	f=1.0MHz	-	1.3	-	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$\text{I}_S=20\text{A}$, $\text{V}_{\text{GS}}=0\text{V}$	-	-	1.2	V
t_{rr}	Reverse Recovery Time ²	$\text{I}_S=10\text{A}$, $\text{V}_{\text{GS}}=0\text{V}$,	-	41	-	ns
Q_{rr}	Reverse Recovery Charge	$d\text{I}/dt=100\text{A}/\mu\text{s}$	-	59	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board, t \leq 10sec, 60°C/W at steady state.
- 4.Starting $T_j=25^\circ\text{C}$, $\text{V}_{\text{DD}}=30\text{V}$, $\text{L}=0.1\text{mH}$, $\text{R}_G=25\Omega$, $\text{I}_{\text{AS}}=24\text{A}$.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

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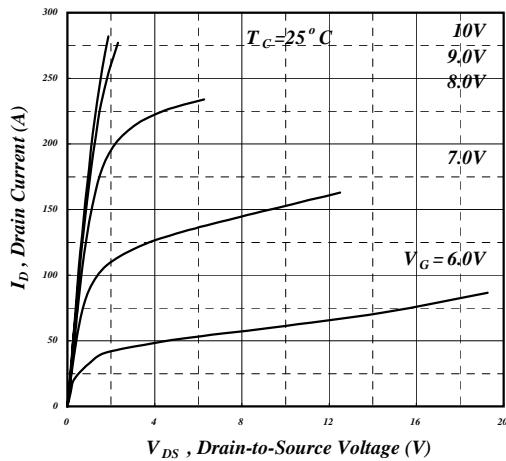


Fig 1. Typical Output Characteristics

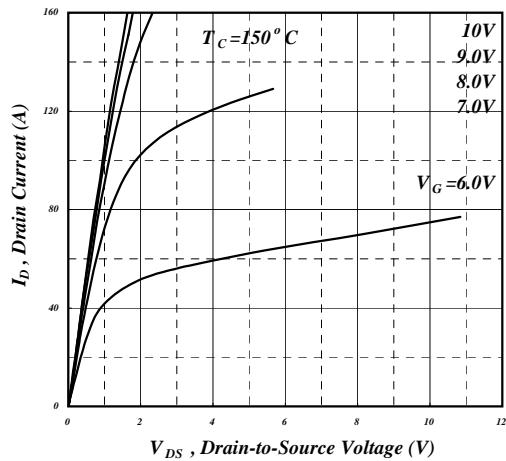


Fig 2. Typical Output Characteristics

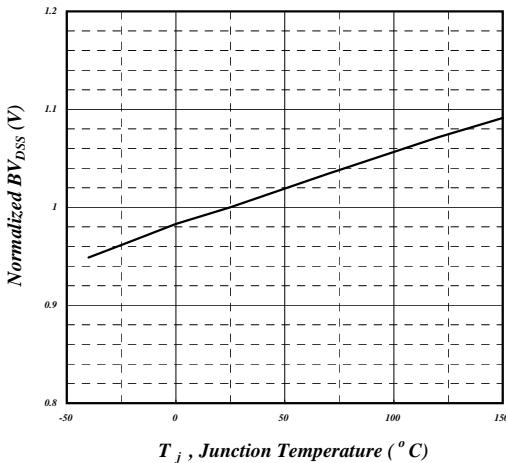
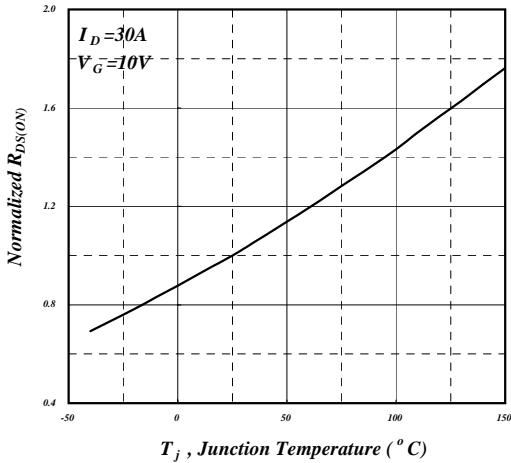
Fig 3. Normalized BV_{DSS} v.s. Junction Temperature

Fig 4. Normalized On-Resistance v.s. Junction Temperature

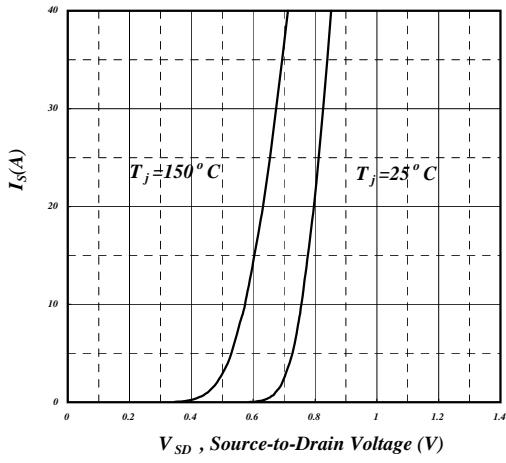


Fig 5. Forward Characteristic of Reverse Diode

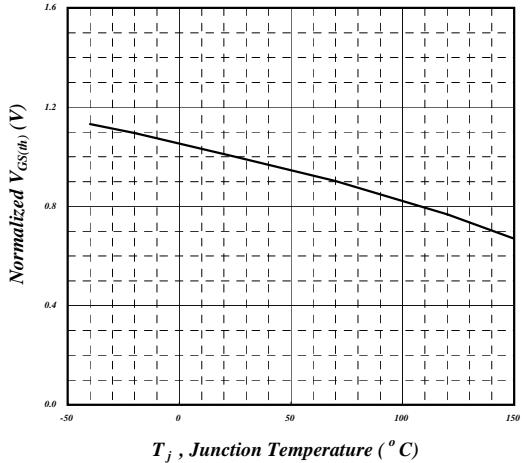


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

